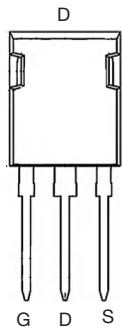




TMG300N10HMP

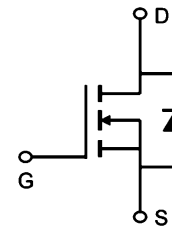
N-Channel Enhancement Mosfet

<p>General Description</p> <ul style="list-style-type: none"> • Low RDS(ON) • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM 	<p>General Features</p> <p>$V_{DS}=100V$ $I_D = 300A$ $R_{DS(ON)}= 2.0\ m\Omega(\text{typ.}) @ V_{GS}= 10V$</p> <p>100% UIS Tested 100% R_g Tested</p>
--	---



Marking: G300N10

MP:TO-247-3L



Absolute Maximum Ratings: ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current- $T_C=25^\circ C$	300	A
	Continuous Drain Current- $T_C=100^\circ C$	163	
I_{DM}	Pulsed Drain Current	1028	
EAS	Single Pulse Avalanche Energy	583	mJ
AS	Avalanche Current	54	A
P_D	Power Dissipation	379	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +175	$^\circ C$

Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.33	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	59	



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Electrical Characteristics (T_J= 25°C unless otherwise specified):

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	100	---	---	V
ΔBV _{DSS} /ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =1mA	---	---	---	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =20A	---	2.0	2.6	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	2	3	4	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	---	---	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =100V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =100V, V _{GS} =0V, T _J =100°C	---	---	100	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =20A	---	76	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	2.3	---	Ω
Q _g	Total Gate Charge	V _{DS} =50V, V _{GS} =10V, I _D =20A	---	150	---	nC
Q _{gs}	Gate-Source Charge		---	32.5	---	
Q _{gd}	Gate-Drain Charge		---	49	---	
T _{d(on)}	Turn-On Delay Time	V _{GS} =10V, V _{DD} =50V, RG=3Ω, ID=20A	---	27	---	ns
T _r	Rise Time		---	78.5	---	
T _{d(off)}	Turn-Off Delay Time		---	110	---	
T _f	Fall Time		---	86	---	
C _{iss}	Input Capacitance	V _{DS} =50V, V _{GS} =0V, f=1MHz	---	9030	---	pF
C _{oss}	Output Capacitance		---	1505	---	
C _{rss}	Reverse Transfer Capacitance		---	40	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,4}	V _G =V _D =0V, Force Current	---	---	300	A
I _{SM}	Pulsed Source Current ^{2,4}		---	---	1000	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1.2	V
t _{rr}	Reverse Recovery Time	IF = 20A, di/dt =100A/μs	---	90	---	nS
Q _{rr}	Reverse Recovery Charge		---	175	---	nC



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Typical Characteristics

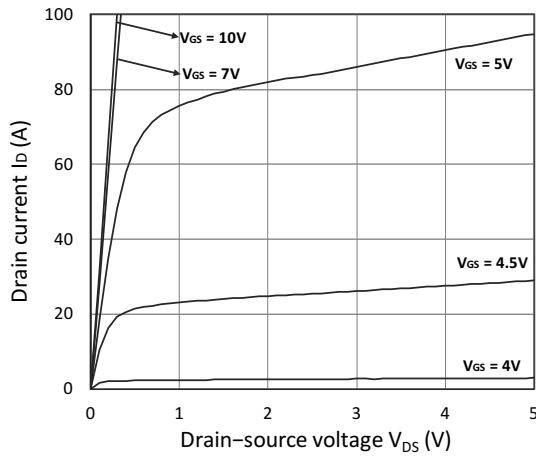


Figure 1. Output Characteristics

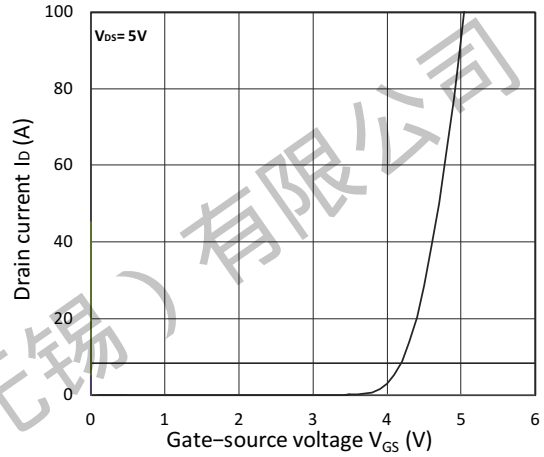


Figure 2. Transfer Characteristics

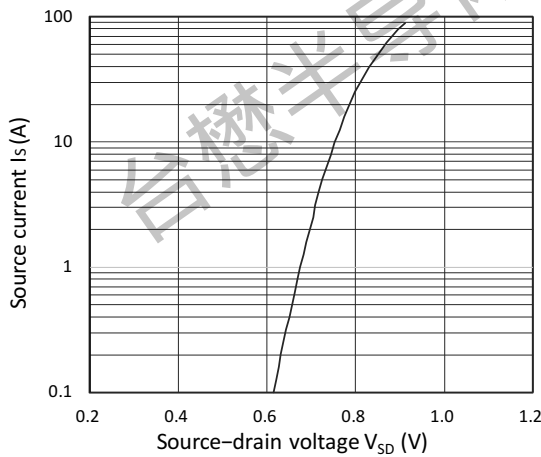


Figure 3. Forward Characteristics of Reverse

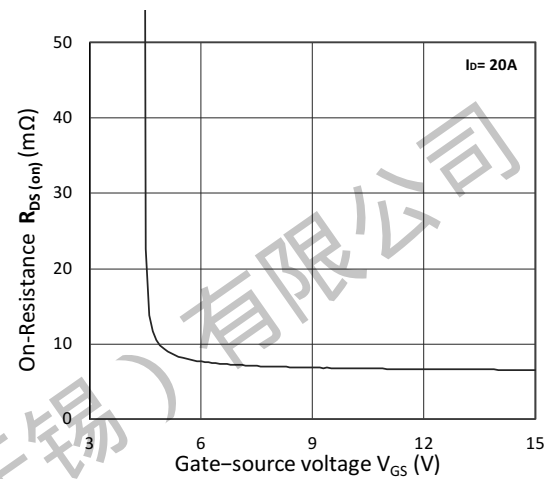


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

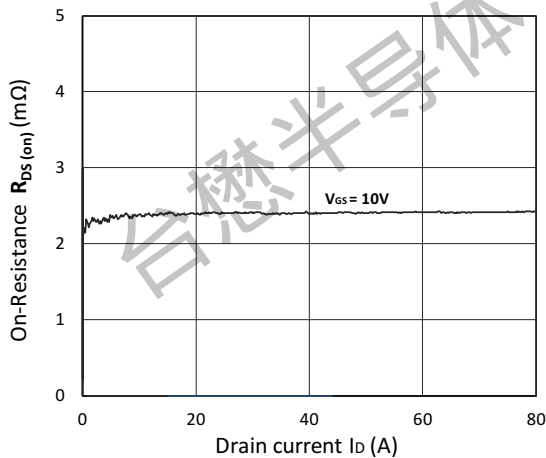


Figure 5. $R_{DS(ON)}$ vs. I_D

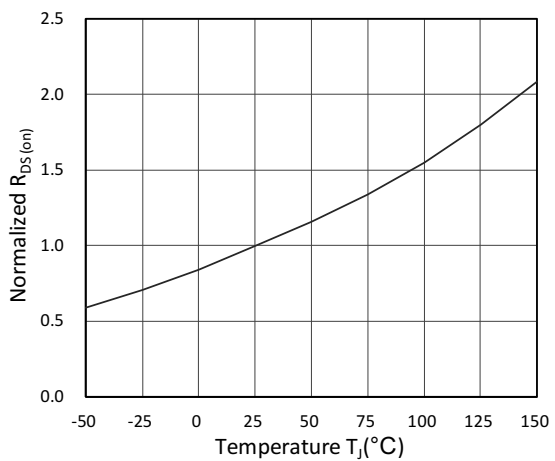


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature



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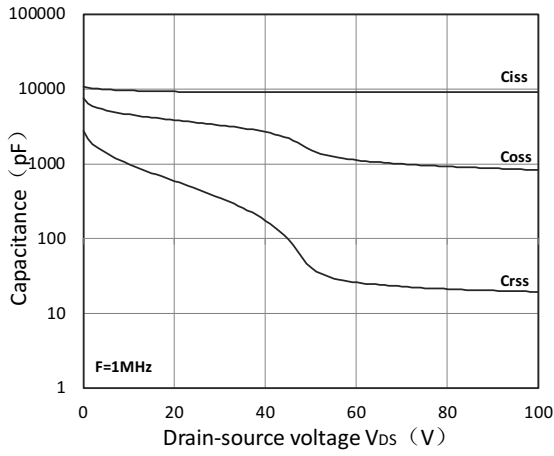


Figure 7. Capacitance Characteristics

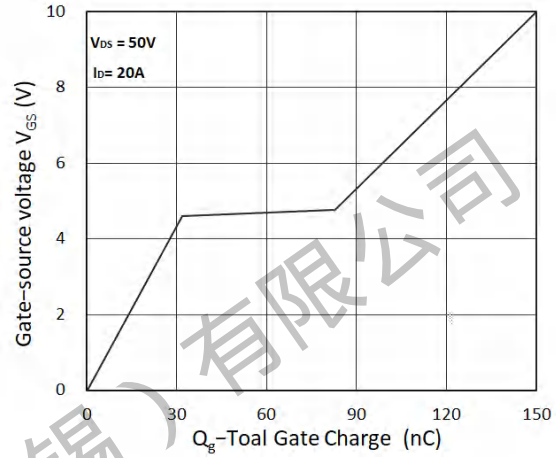


Figure 8. Gate Charge Characteristics

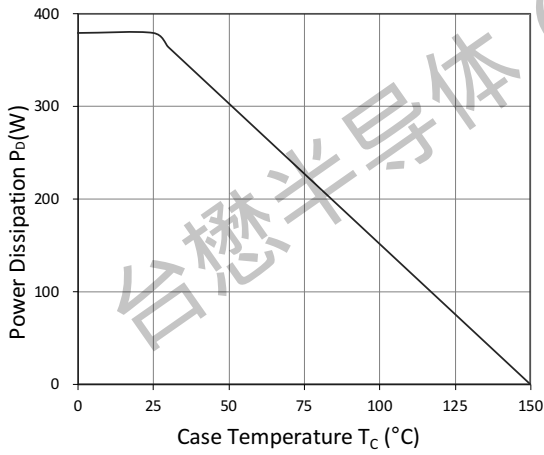


Figure 9. Power Dissipation

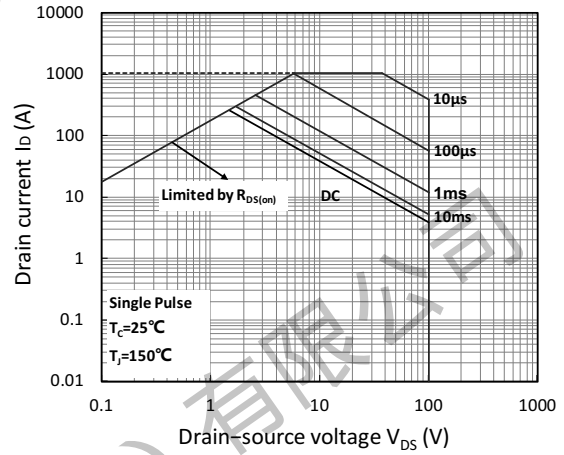


Figure 10. Safe Operating Area

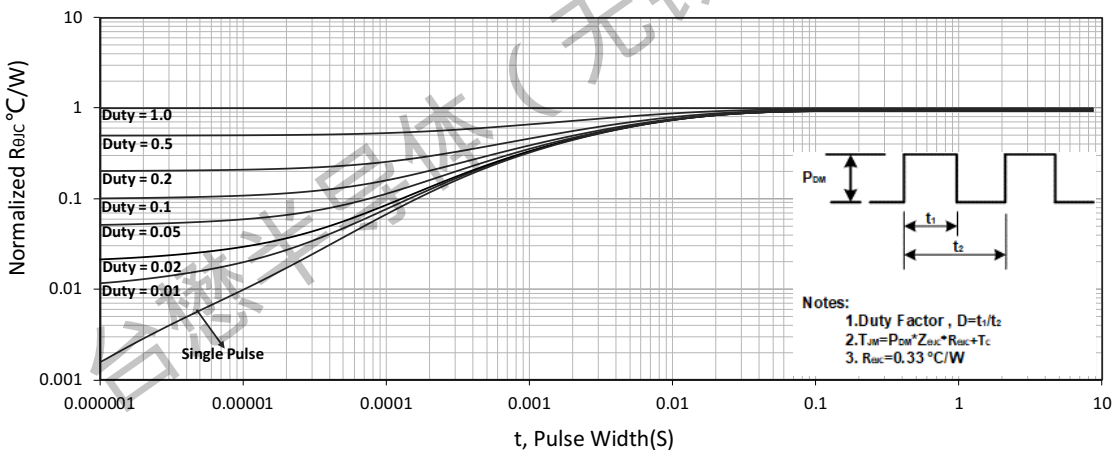


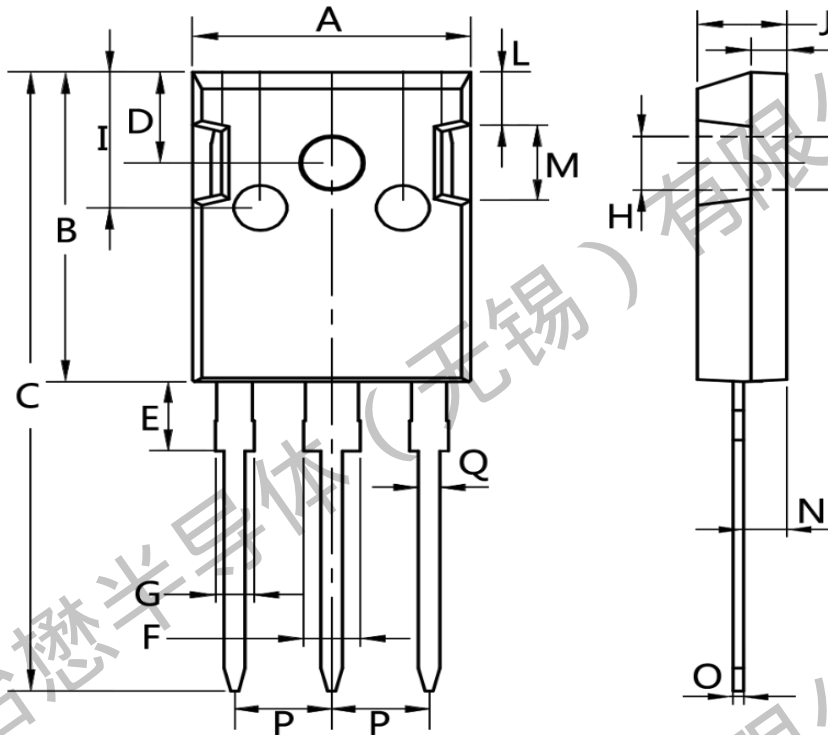
Figure 11. Normalized Maximum Transient Thermal Impedance



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Package Mechanical Data :TO-247-3L

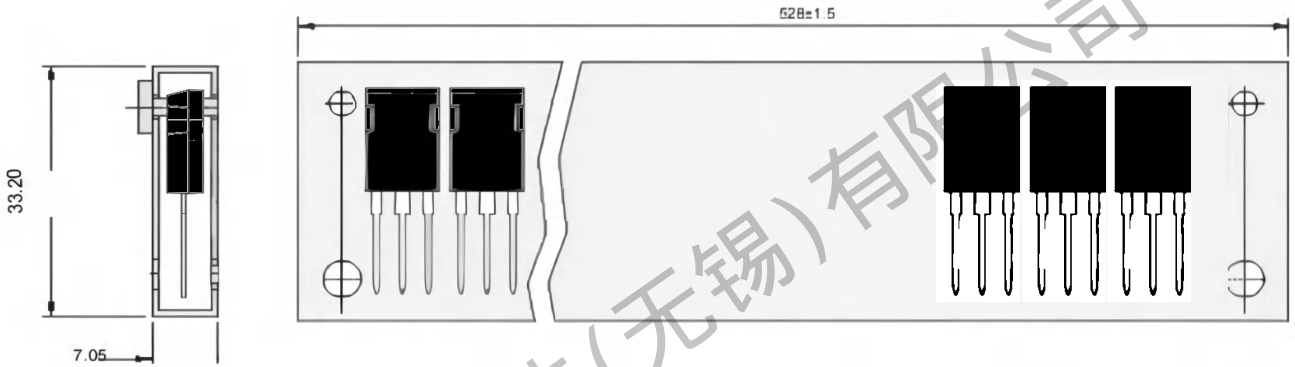


Dim.	Min.	Max.
A	15.0	16.0
B	20.0	21.0
C	41.0	42.0
D	5.0	6.0
E	4.0	5.0
F	2.5	3.5
G	1.75	2.5
H	3.0	3.5
I	8.0	10.0
J	4.9	5.1
K	1.9	2.1
L	3.5	4.0
M	4.75	5.25
N	2.0	3.0
O	0.55	0.75
P	Typ 5.08	
Q	1.2	1.3



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All Dimensions are in mm

1.TO-247-3L Packaging

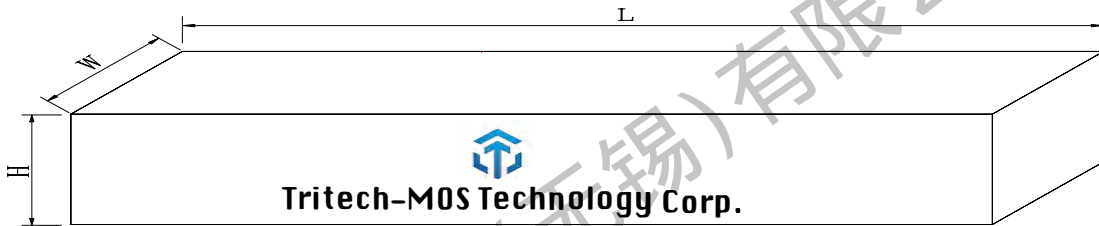
Package	Packing Form	Quantity		
		Tube	Inner Box [kpcs]	Outbox [kpcs]
TO-247-3L	Tube Tape	30	5	1



TMG300N10HMP

N-Channel Enhancement Mosfet

Inner Box



Dimension : 580 (L)×154(W) ×49(H) mm

Quantity : 30 ×15Ea = 450pcs Or 30 ×20Ea = 600pcs

Outer Box



Dimension : 595(L)×285(W) ×185(H) mm

Quantity : 450×5Ea = 2250pcs Or 600 ×5Ea = 3000pcs



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Revision history:

Date	Rev	Description	Page
2023.08.01	23.08	Original	